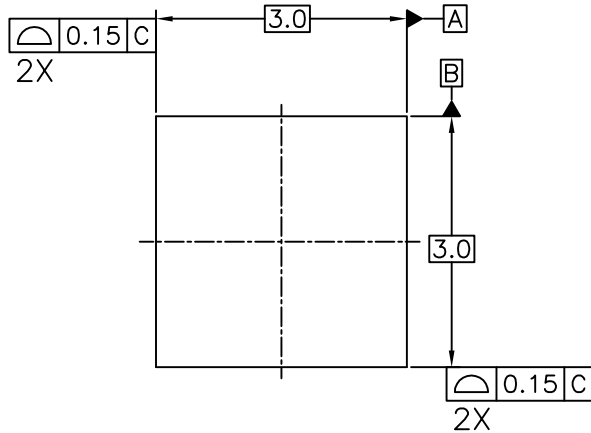
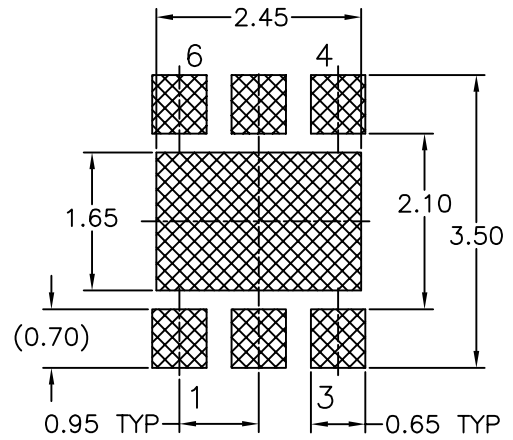


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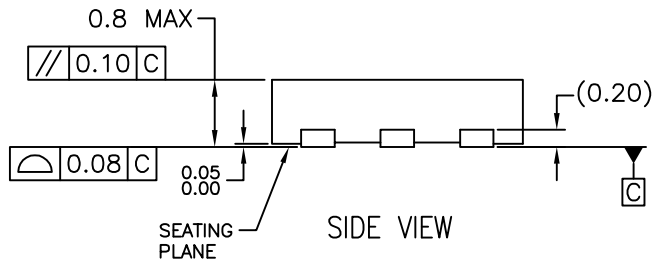
REVISIONS				
LTR	DESCRIPTION	EDCN	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL		10-2-2003	FEITAN



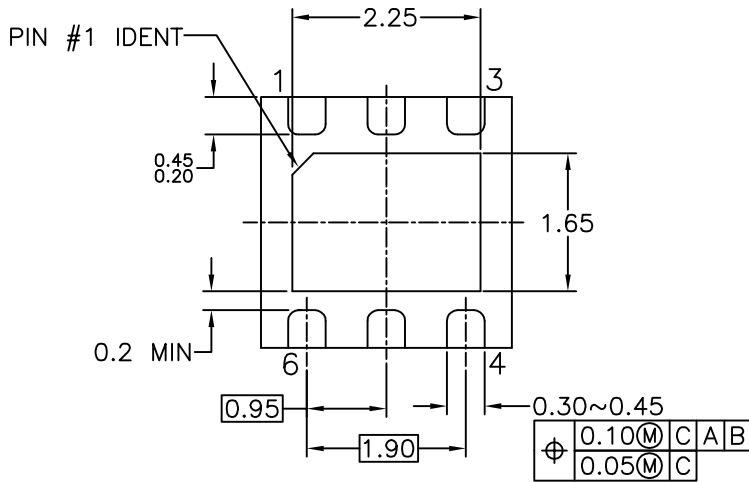
TOP VIEW



RECOMMENDED LAND PATTERN



SIDE VIEW



BOTTOM VIEW

NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-229, VARIATION WEEA, DATED 11/2001
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994

MLP06DrevA

APPROVALS	DATE	FAIRCHILD SEMICONDUCTOR™			
DRAWN FEITAN	6-2-2003	Bayan Lepas, FIZ, 11900, Penang, Malaysia.			
DFTG. CHK.		6LD,MLP,JEDEC MO-229, DUAL 3MM SQUARE			
ENGR. CHK.					
		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	N/A	MKT-MLP06D	A
DO NOT SCALE DRAWING				SHEET 1 of 1	